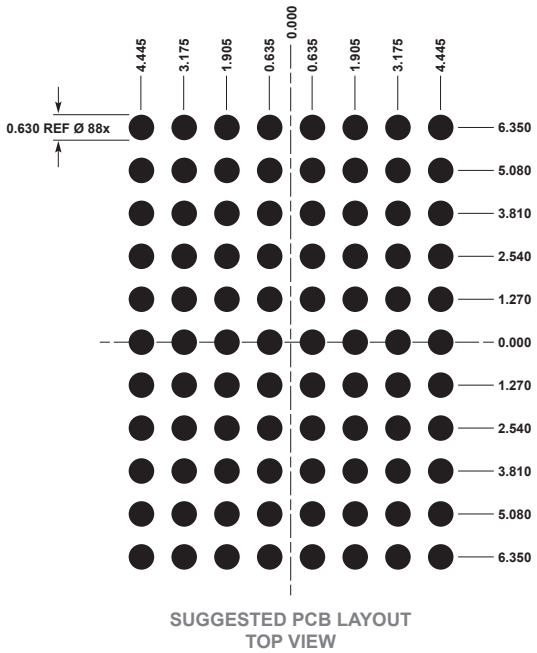
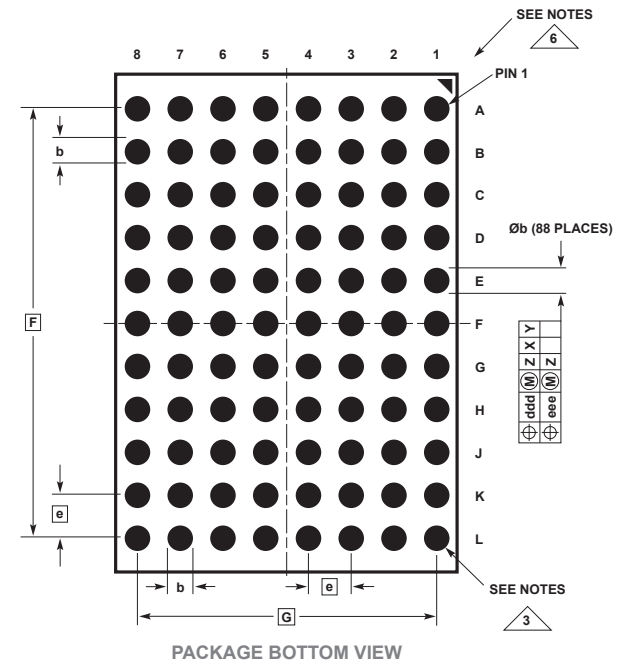
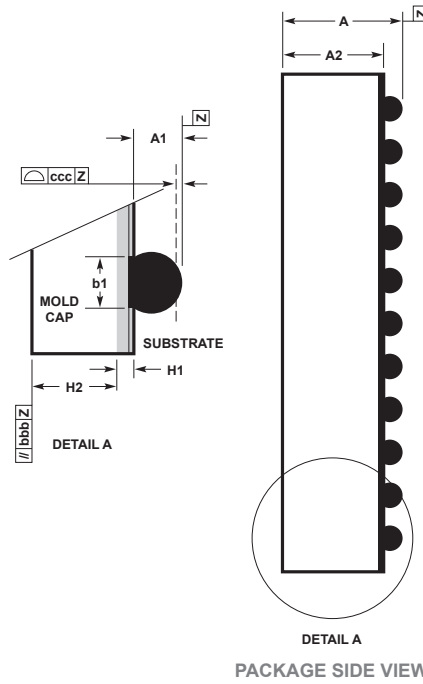
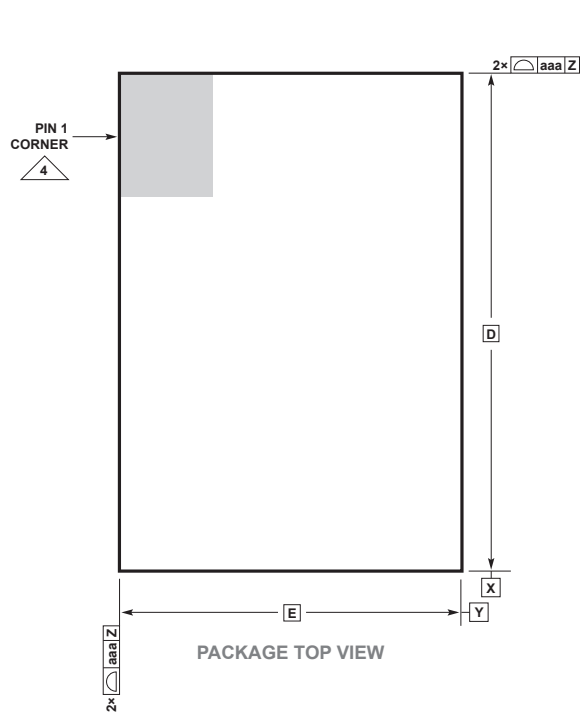


**88-Ball Chip Scale Package Ball Grid Array [CSP_BGA]
15mm × 11.25mm × 3.42mm
(Reference DWG # 05-08-1928)**



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	3.22	3.42	3.62	
A1	0.50	0.60	0.70	BALL HT
A2	2.72	2.82	2.92	
b	0.60	0.75	0.90	BALL DIMENSION
b1	0.60	0.63	0.66	PAD DIMENSION
D	15.00			
E	11.25			
e	1.27			
F	12.70			
G	8.89			
H1	0.32 REF			SUBSTRATE THK
H2	2.50 REF			MOLD CAP HT
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.30	
eee			0.15	

TOTAL NUMBER OF BALLS: 88

- NOTES:**
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 2. ALL DIMENSIONS ARE IN MILLIMETERS
 3. BALL DESIGNATION PER JEP95
 4. DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN 1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
 5. PRIMARY DATUM -Z- IS SEATING PLANE
 6. PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY